



**Electronics
System-
Integration
Technology
Conference**

WELCOME TO IEEE ESTC 2026

Conference Scope

Organized by IEEE-EPS since 2006, the IEEE Electronics System-Integration Technology Conference (IEEE ESTC) series is the premier event covering latest developments in packaging technology and new applications.

IEEE ESTC completes the triumvirate together with ECTC in the United States and EPTC in Singapore and thus supports the global community of electronics packaging engineers and scientists.

About Helsinki

Helsinki, Finland's vibrant capital, blends Nordic charm with cutting-edge innovation. Known for its sleek architecture, design culture, and proximity to nature, the city is also a global hub for modern technologies.

Home to a thriving startup ecosystem, world-class universities and pioneering research in AI, gaming and sustainability, Helsinki attracts entrepreneurs and tech talent from across the globe. Its forward-looking mindset, combined with strong public-private collaboration, positions Helsinki as a dynamic center for digital transformation and future industries.

CONTACT

Conference Office

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General Chair

Toni Mattilla
Business Finland

Technical Program Chair

Grace O'Malley
iNemi Ireland

Exhibition Chair

Steffen Kröhnert
ESPA-Consulting

More Information

www.estc-conference.net





CONFERENCE TOPICS

The technical program will include oral talks, poster presentations, an exhibition, special sessions and invited keynote talks given by renowned speakers. The following topics will be covered:

- Advanced packaging
- Materials for interconnects and packaging
- Optoelectronic systems packaging
- Assembly and manufacturing technologies
- Design tools and modeling
- Power electronics system packaging
- Advanced technologies for emerging system
- Reliability of electronic devices and systems
- Flexible, printed and hybrid electronics
- RF, mm-wave and THz systems packaging
- Global education for electronics

Abstract submission

Abstract submission will open on December 1, 2025.



EXHIBITOR PACKAGES

The conference provides your company or institution strong visibility and access to more than 300 engineers, managers, and decision makers from all areas of the microelectronics and system-integration industry, academics, and research institutes. These include material, equipment, software tools, design and simulation, processes and services for semiconductor assembly, interconnect, packaging, test, process control and analysis technologies as well as market research.

We offer the following options for exhibitors

Premium Booth*:	6,400 €
Standard Booth*:	4,200 €

SPONSORING PACKAGES

There are several ways to become a supporter of the 11th IEEE ESTC. Participation for instance as a main sponsor – Silver, Gold, and Platinum Sponsorship Packages available – offers your company or institution an excellent way to significantly increase visibility and getting recognized at the event with a combination of promotional, on-site representation and content-related benefits all together in a value-priced package.

Conference breaks sponsor*:	2,400 €
Proceedings sponsor*:	3,500 €
Conference bag sponsor*:	5,200 €
Silver sponsor*:	7,000 €
Gold sponsor*:	12,200 €
Platinum sponsor*:	18,600 €

For more information, please contact exhibition@estc-conference.net

* valid until April 30, 2026, includes 25.5% Finnish VAT